

Certificate of "Facsimile Transmission" Under 37 C.F.R. 1.8(a)	
"Date of Deposit:	<u>Nov. 8, 2004</u> PTO Central Facsimile No: <u>703-872-9306</u>
I hereby certify that this paper and/or fee is being transmitted to the United States Patent and Trademark Office by "Facsimile Transmission" service under 37 C.F.R. 1.8(a) on the date indicated above and at a central facsimile number provided by MPEP 502.01 [I(A)], and is addressed to Commissioner For Patents, PO Box 1450, Alexandria, VA 22313-1450.	
<u>Irene Hu</u>	<u>Irene Hu</u>
Print Name	Signature:

RECEIVED
CENTRAL FAX CENTER

NOV 08 2004

VIA FACSIMILE: 703-872-9306
November 8, 2004

MS AMENDMENT
Commissioner For Patents
PO Box 1450
Alexandria, VA 22313-1450

Re: U.S. Utility Patent Application
Appl. No.: 10/658,431; Group Art Unit: 2839
Filed: 09/08/2003 Examiner: Prasad, C.
Inventor(s): Chang, et al. Atty Docket No.: IAT-P002

For: "Integrated Multi-Chip Connector Module And Method"

Dear Sir:

The following documents are forwarded herewith for action by the U.S. Patent and Trademark Office:

1. Form PTO-1082;
2. Amendment (12 pages)

Respectfully submitted,

Irene Hu
Irene Hu
Reg. No. 34,625

Irene Hu, Esq.
2033 Ralston Ave., PMB #146
Belmont, CA 94002

11-8-2004
Date

PH: (40) 280-0523
FAX: 650) 598-0116
EMAIL: ihu@sbcglobal.net

Fax: 650.598.0116

Irene Hu, Patent Attorney, 2033 Ralston Ave., #14, Belmont, CA 94002
Phone: 650.280.0523

Email: ihu@sbcglobal.net

Certificate of "Facsimile Transmission" Under 37 C.F.R. 1.8(a)	
<p>Date of Deposit: <u>Nov. 8, 2004</u> PTO Central Facsimile No: 703-872-9306 I hereby certify that this paper and/or fee is being transmitted to the United States Patent and Trademark Office by "Facsimile Transmission" service under 37 C.F.R. 1.8(a) on the date indicated above and at a central facsimile number provided by MPEP 502.01 [(A)], and is addressed to Commissioner For Patents, PO Box 1450, Alexandria, VA 22313-1450.</p>	
<u>Irene Hu</u>	<u>Irene Hu</u>
Print Name	Signature

VIA FACSIMILE: 703-872-9306
November 8, 2004

RECEIVED
CENTRAL FAX CENTER

NOV 08 2004

Mail Stop: Amendment
Commissioner For Patents
PO Box 1450
Alexandria, VA 22313-1450

AMENDMENT TRANSMISSION LETTER

Sir:

Transmitted herewith for filing relating to U.S. Patent Application of
 Application No.: 10/658,431 Group Art Unit: 2839
 Filed: 09/08/2003 Examiner: Prasad, C.
 Inventor(s): Chang, et al. Atty. Docket No: JAT-F002

Entitled: "Integrated MultiChip Connector Module And Method"

Associated Filing Documents Enclosed:

- Cover Sheet For Enclosed Documents
 Amendment: Response/Amendment 12 pages total

FEES DUE

- Applicant Claims Small Entity Status (37 CFR 1.27)

The fees due associated with this correspondence pursuant to 37 C.F.R. 1.16 and for recording the Assignment, if any, are determined as follow:

		CLAIMS			
	No. of Claims		Extra Claims	Rate	Fees
Basic Application Fee (\$770 large entity; \$385 small entity)					\$ 00.00
Total Pending Claims In Application	11	Minus Basic Allowed 20 =		X \$18 = X \$ 9 (small) =	\$ 00.00
Adjustment: Prior Paid Claims		Minus Prior Paid 20 =		X \$18 = X \$ 9 (small) =	- (\$ 00.00)
Total Current Independent Claims	2	Minus Prior Paid 3 =	0	X \$86 = X \$43 (small) =	\$ 00.00
If Multiple Dependent Claims are presented, add \$280.00 or \$140.00 (small)					
If Assignment enclosed, add Assignment Recording Fee \$40.00					
TOTAL APPLICATION FEE DUE					\$ 00.00

PAYMENT OF FEES

The full fee due in connection with this communication is

\$ 00.00

Fax: 650.598.0116

Irene Hu, Patent Attorney, 2033 Ralston Ave., #14, Belmont, CA 94002
 Phone: 650.280.0523

Email: i_hu@icloudglobal.net

and is provided as follows:

- The Commissioner is hereby authorized to charge the fees associated with this communication or credit any overpayment to Deposit Account No: 502465.
- A Check No. _____ for \$ 00.00 is enclosed. However, the Commissioner is hereby also authorized to charge any additional necessary amount associated with this communication or credit any overpayment to Deposit Account No: 502465.
- No fee required. However, the Commissioner is hereby also authorized to charge any necessary additional amount associated with this communication or credit any overpayment to Deposit Account No: 502465.

NO 18 MONTHS PUBLICATION

REQUEST AND CERTIFICATION UNDER 35 U.S.C. 122(b) (1) (B) (i)

- I hereby certify that the invention disclosed in the attached application has not and will not be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen month after filing. I hereby request that the attached application not to be publish under 35 U.S.C. 122(b).
- Request previously filed.

Please direct all correspondence concerning the above-identified application to the following address:

Irene Hu
2033 Ralston Ave., #146
Belmont, CA 94002
(650) 280-0523
(650) 598-0116; Fax
Email: i_hu@sbcglobal.net

Respectfully submitted,


Irene Hu

Reg. No. 34,625

Rev. 10/05/2004

11-8-2004
Date

Irene Hu, Patent Attorney, 2033 Ralston Ave., #146, Belmont, CA 94002
Phone: 650.280.0523

Fax: 650.598.0116

Email: i_hu@sbcglobal.net

Certificate of "Facsimile Transmission" Under 37 C.F.R. 1.8(a)	
"Date of Deposit:	Nov. 8, 2004
PTO Central Facsimile No: 703-372-2306	
I hereby certify that this paper and/or fee is being transmitted to the United States Patent and Trademark Office by "Facsimile Transmission" service under 37 C.F.R. 1.8(a) on the date indicated above and at a central facsimile number provided by MPEP 502.01 [(A)], and is addressed to Commissioner For Patents, PO Box 1450, Alexandria, VA 22313-1450.	
Print Name	
Signature	

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

RECEIVED
CENTRAL FAX CENTER

In Re Patent Application:

Inventor: Chang, et al. Atty Docket No.: IAT-P002
5 Serial No.: 10/658,431 Group Art Unit: 2839
Filed: 09/08/2003 Examiner: Prasad, C.
Title: Integrated Multi-Chip Connector Modulo A n-I Method

NOV 08 2004

MS Amendment
10 Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Amendment/Response To A Non-Final Action Under 37 CFR §1.111

15 Dear Sir:

In response to Official Action of 08/27/2004, please amend the above-identified application as provided herein, the contents being organized as follows:

Amendment to the Title begins on page 2.

20 Amendment to the Claims begins on page 3.

Remarks/Arguments begins on page 6

Appl. No.: 10/658,431
Docket No: IAT-P002
Filed: 09/08/2003
Response/ Amendment

Amendment to the Title

Please replace the Title of this application with:

A Multi-Chip Connector Module Having One Or More Semiconductor Die

5

10

a set of input connector pins, each input connector pin further comprising a first end and a second end, wherein the first end is provided to receive an incoming signal, and the second end is electrically connected to the one or more integrated circuits semiconductor dice on the substrate; and

15

a set of output connector pins, each output connector pin further comprising a first and a second end, wherein the first end is electrically connected to the one or more integrated circuits semiconductor dice, and the second end is provided for transmitting a processed signal from the one or more integrated-circuits semiconductor dice as an output signal to the second end of each output connector pin; and

20

a connector housing for encasing the array of substrate assemblies, wherein the housing comprises a first set of signal pin apertures through which extend the set of input connector pins to allow external electrical connection to a first external device, and wherein the housing further comprises a second set of signal pin apertures through which extend the set of output connector pins to allow external electrical connection to a second external device, wherein the connector housing further comprises injection-molding a thermally conductive composite around the array of substrate assemblies to fill a plurality of cavities between the array of substrate assemblies, the injection-molded connector housing thereby forming a semiconductor packaging for the one or more semiconductor dice while securing in place the array of substrate assemblies, the one or more semiconductor dice, and the plurality of input and output connector pins.

25

2. (Original) The integrated multi-chip connector module of Claim 1 wherein each substrate assembly further comprises a set of pin anchoring means, the set of pin anchoring means anchors the input or output connector pins to the substrate assembly.

30

3. (Original) The integrated multi-chip connector module of Claim 1 wherein the second end of each input or output connector pin terminates in an electrically conductive pad.

40